

BGA Soldering Recommendations

1. Use #4 solder paste for best results.
2. Place Adapter board in your development board for stability during pasting. Alternatively, place the Adapter in a foam base (provided) for stability during pasting.
3. Place the stencil over the pins. Confirm it is flat on the board (no arching).
4. Confirm the pads are visible and aligned correctly (easiest through a microscope).
5. Use any appropriately size tool to squeegee the paste through the stencil
6. After pasting, remove the board from the dev board and hold by the pins with one hand. With the other hand pull the stencil straight up off the pins. Pulling at an angle may pull solder paste off some or all of the pads.
7. Correctly place the SMD part onto the pasted board.
8. Using a hot air gun, apply heat carefully to the top of the part.
Temperature set point 360 C - 400 C (use lower temperature to start).
Air flow should be low enough so that the part is not jostled or blown off the board.
Reflow should occur in 10 to 15 seconds possibly less.
9. Probe the through hole pins to confirm that all of the BGA balls have collapsed and are electrically connected to the board.